

Proposal for compact module products

Concept

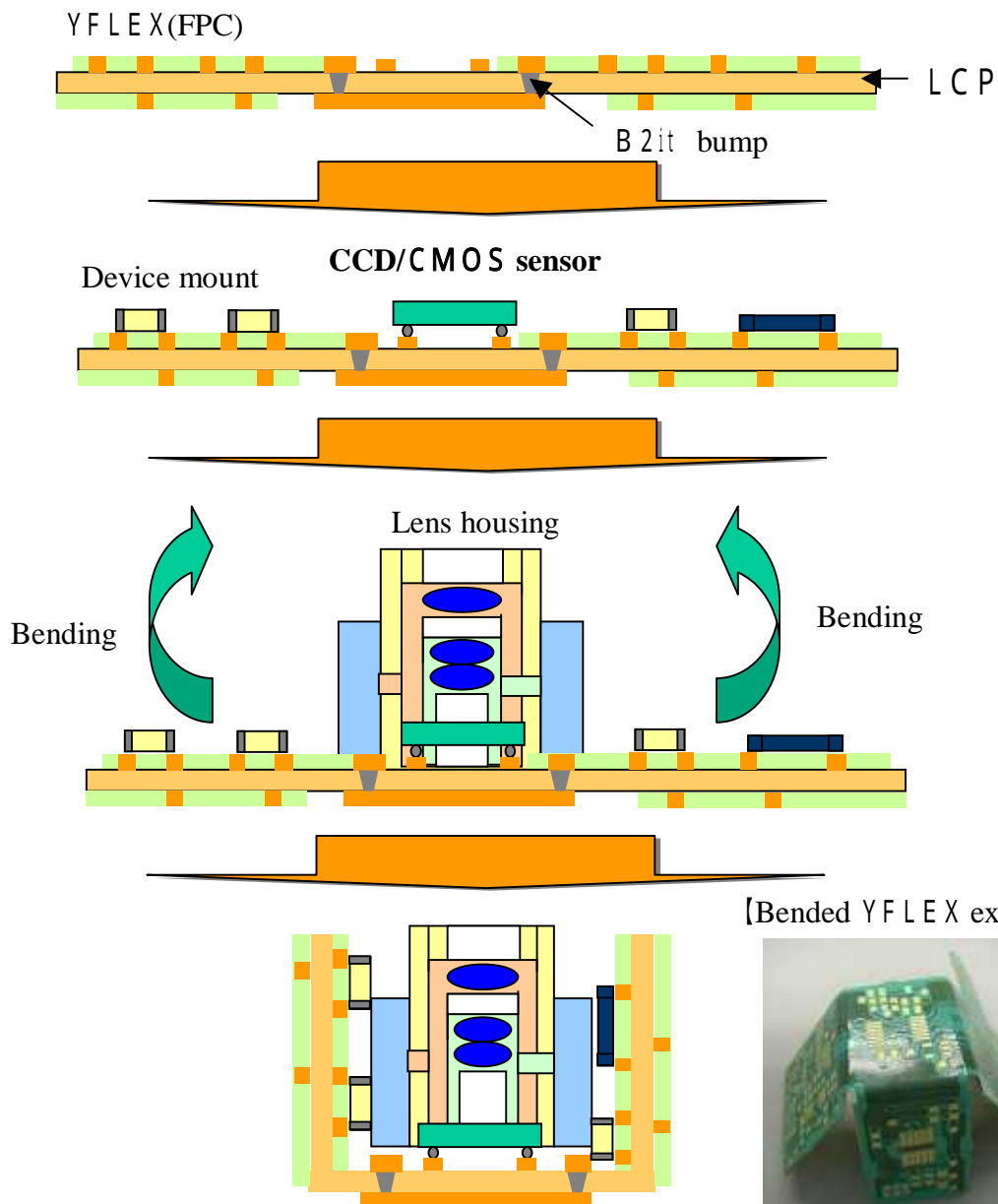
Bend formation after device mounting on YFLEX(B2it, Double sides LCP FPC)
Realizes compact module

Contents

Proposal :3D structure performed by bending after device mounting

Proposal :Bending structure may realize imbedded structure

Proposal :3D structure performed by bending after device mounting





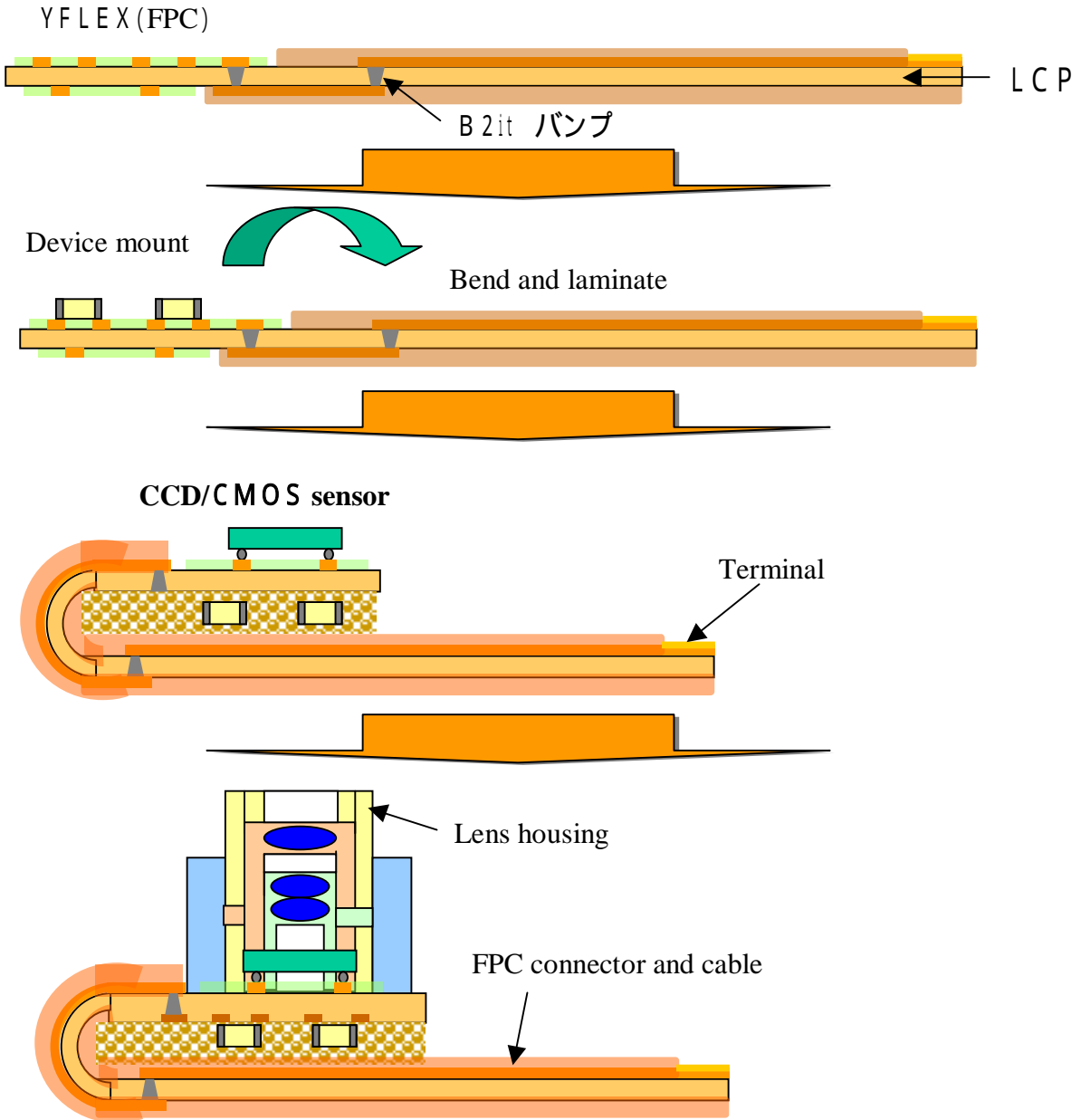
YAMAICHI
ELECTRONICS

Device mounting board

Better
connection

[Patent pending]

Proposal : Bending structure may realize imbedded structure



【YFLEX bended and laminated example】

